

What is claimed is:

1. A high-frequency circuit comprising:
 - a substrate having an electronic component on an obverse side thereof;
 - a first ground pattern formed on almost an entire reverse side of the substrate;
 - a microstrip line formed on the obverse side of the substrate; and
 - a bias line connected to the electronic component on the obverse side of the substrate and formed continuously on the obverse side and the reverse side of the substrate so as to cross the microstrip line on the reverse side of the substrate in plan view so as to supply a bias voltage to the electronic component,wherein the first ground pattern is formed so as to circumvent the bias line formed on the reverse side of the substrate;
 - a portion of the first ground pattern that circumvents the bias line on the reverse side of the substrate is continuously formed on the obverse side of the substrate as a second ground pattern so as to divide the microstrip line in two parts; and
 - a chip jumper is arranged to bridge the two divided parts of the microstrip line over the second ground pattern so as to connect the divided microstrip line electrically.
2. A high-frequency circuit as claimed in claim 1,
 - wherein a plurality of bias lines are formed so as to cross, in plan view, the chip jumper arranged to bridge the two divided parts of the microstrip line.
3. A high-frequency circuit as claimed in claim 1,
 - wherein the microstrip line connected by the chip jumper is connected to a band-pass filter.

4. A high-frequency circuit as claimed in claim 1,
wherein the chip jumper is a metal plate.
5. A high-frequency circuit as claimed in claim 1,
wherein the chip jumper is a chip capacitor.
6. A high-frequency circuit as claimed in claim 1,
wherein the chip jumper is a chip inductor.
7. A high-frequency circuit as claimed in claim 1,
wherein the chip jumper is a chip resistor.
8. A high-frequency circuit as claimed in claim 1,
wherein the first ground pattern and the second ground pattern are connected together
electrically by way of a through hole.
9. A high-frequency circuit having a substrate, a first ground pattern formed on
almost an entire reverse side of the substrate, and a first microstrip line and a second
microstrip line formed on the substrate,
wherein the first microstrip line is formed on an obverse side of the substrate;
the second microstrip line is formed continuously on the obverse side and the reverse
side of the substrate so as to cross the first microstrip line on the reverse side of the substrate
in plan view;

the first ground pattern is formed so as to circumvent the second microstrip line formed on the reverse side of the substrate;

a portion of the first ground pattern that circumvents the first microstrip line on the reverse side of the substrate is continuously formed on the obverse side of the substrate as a second ground pattern so as to divide the first microstrip line in two parts; and

a chip jumper is arranged to bridge the two divided parts of the first microstrip line over the second ground pattern so as to electrically connect the divided two parts of the first microstrip line.

10. A high-frequency circuit as claimed in claim 9,
wherein a plurality of second microstrip lines are formed so as to cross, in plan view,
the chip jumper arranged to bridge the two divided parts of the first microstrip line.

11. A high-frequency circuit as claimed in claim 9,
wherein the first microstrip line connected by the chip jumper is connected to a band-
pass filter.

12. A high-frequency circuit as claimed in claim 9,
wherein the chip jumper is a metal plate.

13. A high-frequency circuit as claimed in claim 9,
wherein the chip jumper is a chip capacitor.

14. A high-frequency circuit as claimed in claim 9,

wherein the chip jumper is a chip inductor.

15. A high-frequency circuit as claimed in claim 9,
wherein the chip jumper is a chip resistor.

16. A high-frequency circuit as claimed in claim 9,
wherein the first ground pattern and the second ground pattern are connected together
electrically by way of a through hole.